

AMENDMENST TO THE CLAIMS

1.-7. (Canceled)

8. (Currently Amended) An apparatus, comprising:
a heat spreader comprising heat conductive material and a non-contiguous wall structure
extending from a surface of the heat spreader; and
a flexible material coupled to the wall structure and to couple to a package substrate.

9. (Previously Presented) The apparatus of claim 8, wherein the flexible material
comprises polymeric sealant material.

10. (Currently Amended) The apparatus of claim 8, wherein ~~said body~~the heat spreader is
plated with nickel.

11. (Currently Amended) The apparatus of claim 8, wherein ~~said body~~the heat spreader is
coated with a heat-conductive organic material.

12.-17. (Canceled)

18. (Currently Amended) A semiconductor package, comprising:
a substrate having a top surface;
at least one semiconductor device ~~attached to said~~coupled to the top surface of ~~said the~~
substrate; and

a cover ~~secured to said~~coupled to the top surface of the substrate through a flexible
sealant material and creating a space between ~~said the~~ substrate and ~~said the~~ cover, ~~said the~~
semiconductor device residing within ~~said space and secured to said substrate and said the space,~~
and the cover comprised of a heat-conductive material,

wherein the cover comprises a plurality of mechanical attachment structures extending
from a surface thereof and the coupling of the cover to the top surface of the substrate comprises
coupling the plurality of mechanical attachment structures to the surface of the substrate.

19. (Original) The semiconductor package of claim 18, wherein the cover is a heat spreader.

20.-23. (Canceled)